

IN THE SPECIFICATION:

Please amend the specification as follows:

Paragraph beginning on page 4, at prenumbered line 25, has been amended as follows:

[0024] Also referring to FIG. 3B, a bottom view of the LCD 10 of FIG. 3A is shown, in which a grounding pin 530 is extended from a blank edge of the PCB 500b (i.e., the side without connecting flexible flat cables 510). A conductive film 520 is taped to the grounding pin 530 and a portion of the nearby metal frame 100b, such that an electrical transmission path can be established to transport segregated charges on the PCB 500 to the environment. A surface area of the conductive film 520 is smaller than that of the PCB 500. Furthermore, the conductive film 520 can also be attached on the plastic frame 200 to fix the PCB 500.

Paragraph beginning on page 5, at prenumbered line 8, has been amended as follows:

[0026] In the foregoing embodiment of FIG. 3B, only one grounding pin 530 is used. However, to achieve a better charge-removing efficiency, a second embodiment having two grounding pins 530 formed on the PCB 500 is shown in FIG. 4A. The two grounding pins 530 are extended from opposite blank edges of the PCB 500b without connecting flexible flat cables 510, and each of the conductive films 520 are taped respectively on the grounding pin 530, the adjacent plastic frame 200, and the nearby sidewall of the metal cover 100b. It is noted that a sum of the surface area of the two conductive films 520 is smaller than that of the PCB 500.

Paragraph beginning on page 5, at prenumbered line 30, has been amended as follows:

[0030] Furthermore, to ensure the passivation film 540 to be perfectly attached on the PCB 500 so as to achieve perfectly electric shielding event, as shown in FIG. 4D, the conductive tape 560 is taped around all four edges of the PCB 500 to form a larger attaching area and a better adhering effect upon the passivation film 540.

It is noted that the surface area of the conductive tape 560 is still smaller than that of the PCB 500.